Atty Docket No. JCLA11476-R2

Serial No.: 10/695,018

REMARKS

Present Status of the Application

This is a full and timely response to the Office Action mailed on January 11, 2006. The Office Action has rejected claims 1-19 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Vinson et al (US 6,700,794, hereinafter "Vinson").

Upon traversing of the outstanding Office Action in this response, claims 1-19 remain pending in the present application.

The Applicants have most respectfully considered the remarks set forth in this Office Action. Regarding the obviousness rejections, it is strongly believed that the cited references are deficient to adequately teach the claimed features as recited in the amended claims. The reasons that motivate the above position of the Applicants are discussed in detail hereafter, upon which reconsideration of the claims is most earnestly solicited.

Response to 35 U.S.C. 103 rejections

Claims 1-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over the AAPA, previously cited, in view of Vinson et al. (US-6,700,794, hereinafter "Vinson"), newly cited.

With regard to the 103(a) rejections of independent claims 1, 9, 14, and 17, Applicants respectfully traverse the 103(a) rejections based upon the following:

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Claims 1, 9, 14, and 17 are amended to include the following limitation: "wherein a metal layer directly formed on the electrodes" and "the metal layer enhances the connection property between the bonding wires and the electrodes". Based upon the previous telephone interview between the Examiner and the Applicant's representative Mr. Jiawei Huang for the present case, it was told that the Examiner had agreed that the metal layers directly formed on the electrodes are not taught by the cited prior art.

Furthermore, evidence presented in the following table also proves that the added claim limitation "wherein a metal layer directly formed on the electrodes" allow claims 1, 9, 14, and 17 to be patentable over the cited prior arts:

Compared Features/ Limitations	Reference # 1 Vinson	Reference # 2 AAPA	Present Invention
Coupling of wire to bonding pad of Capacitor Carrier	YES – FIG. 4A, 17b coupled to 34c	NO	NO – Wire 234, 236 coupled to metal layer 242, which is not equivalent to electrodes or bonding pad 232a, 232b
220, 230, 210, 214, 216, 218 matched one to one	NO	YES - FIG. 1A of the present invention	YES – FIG. 2A of the present invention

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Metal layer on top of electrode of passive component	ИО	NO	YES – FIG. 2A of the present invention
Metal layer coupling to Capacitor Carrier	Metal layer 34b on top of capacitor carrier on 1 side in FIG. 4A	NO	Metal layer is taught to cover over electrode instead.
Bonding Pad coupling to metal layer	Bonding Pad on top of metal layer on one side – 34c on top of 34b on one side, FIG. 4A	NO	Metal layer is taught to cover over electrode.

As a result, claims 1, 9, 14, and 17 are patentable over AAPA in view of Vinson, and should be allowed.

Regarding claims 6 and 10, on page 6 of the Office Action, the Examiner made the following remarks: "...except for the electrodes being Ni, Au or Ni/Au alloy...... it would have been obvious to use these materials for in the electrodes of the passive component", it should be evident that the Examiner had mistakenly identified the metal layer as the electrode; the metal layer and the electrode are clearly two <u>distinct and separate</u> elements, 242 and 232b, respectively, as shown in FIG. 2A of the present invention. Therefore, claims 6 and 10 are patentable over AAPA in view of Vinson, and should be allowed.

Based upon the aforementioned arguments, dependent claims 2-8, 10-13, 15-16, and 18-19 should be allowed pending the allowance of claims 1, 9, 14, and 17.

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CONCLUSION

For at least the foregoing reasons, it is believed that the presently pending claims 1-19 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted, J.C. PATENTS

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